



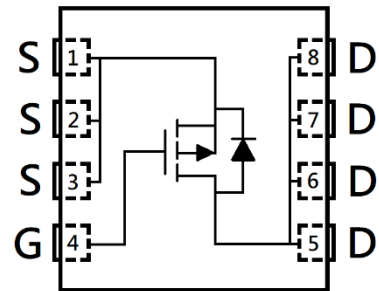
Features

- Low On Resistance
- Low Gate Charge
- Fast Switching Characteristic

BV_{DSS}	-200V
$I_D @ V_{GS} = -10V, T_C = 25^\circ C$	-19A
$I_D @ V_{GS} = -10V, T_A = 25^\circ C$	-3A
$R_{DS(ON) \text{ typ.}} @ V_{GS} = -10V, I_D = -3A$	125m Ω

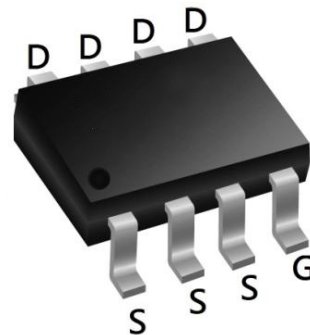
Equivalent Circuit

WLB15P20



G : Gate S : Source D : Drain

SOP8 Pin Configuration



**Absolute Maximum Ratings (T_A=25°C)**

Parameter	Symbol	Limits	Unit	
Drain-Source Voltage	V _{DS}	-200	V	
Gate-Source Voltage	V _{GS}	±20		
Continuous Drain Current @ V _{GS} =-10V, T _C =25°C	I _D	-19	A	
Continuous Drain Current @ V _{GS} =-10V, T _C =100°C		-12		
Continuous Drain Current @ V _{GS} =-10V, T _A =25°C		-3		
Continuous Drain Current @ V _{GS} =-10V, T _A =70°C		-2.4		
Pulsed Drain Current	I _{DM}	-76		
Continuous Body Diode Forward Current @ T _C =25°C	I _S	-19		
Avalanche Current @ L=0.1mH	I _{AS}	-35		
Avalanche Energy @ L=0.5mH	E _{AS}	100	mJ	
Total Power Dissipation	P _D	T _C =25°C	125	W
		T _C =100°C	50	
		T _A =25°C	3.2	
		T _A =70°C	2	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150	°C	

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-case	R _{θJC}	1	°C/W
Thermal Resistance, Junction-to-ambient	R _{θJA}	40	

Note:

- *a. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- *b. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2 oz. copper, in a still air environment with T_A=25°C. The power dissipation P_D is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- *c. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.



Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-200	-	-	V	V _{GS} =0V, I _D =-250μA
V _{GS(th)}	-2	-	-4		V _{DS} =V _{GS} , I _D =-250μA
G _{FS}	-	11	-	S	V _{DS} =-15V, I _D =-3A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	-1	μA	V _{DS} =-160V, V _{GS} =0V
R _{DS(ON)}	-	125	165	mΩ	V _{GS} =-10V, I _D =-3A
Dynamic					
C _{iSS}	-	2484	-	pF	V _{DS} =-100V, V _{GS} =0V, f=1MHz
C _{oSS}	-	127	-		
C _{rSS}	-	71	-		
R _g	-	3.6	-	Ω	f=1MHz
Q _g *1, 2	-	48	-	nC	V _{DS} =-75V, I _D =-3A, V _{GS} =-10V
Q _{gs} *1, 2	-	11	-		
Q _{gd} *1, 2	-	14	-		
t _{d(ON)} *1, 2	-	25	-	ns	V _{DS} =-75V, I _D =-3A, V _{GS} =-10V, R _{GS} =6Ω
t _r *1, 2	-	22	-		
t _{d(OFF)} *1, 2	-	68	-		
t _f *1, 2	-	37	-		
Source-Drain Diode					
V _{SD} *1	-	-0.8	-1.2	V	I _S =-3A, V _{GS} =0V
t _{rr}	-	52	-	ns	I _F =-3A, dI _F /dt=100A/μs
Q _{rr}	-	126	-	nC	

Note:

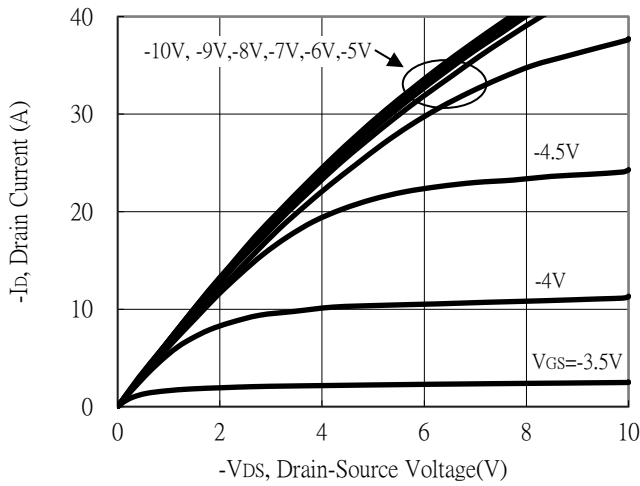
*1. Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

*2. Independent of operating temperature

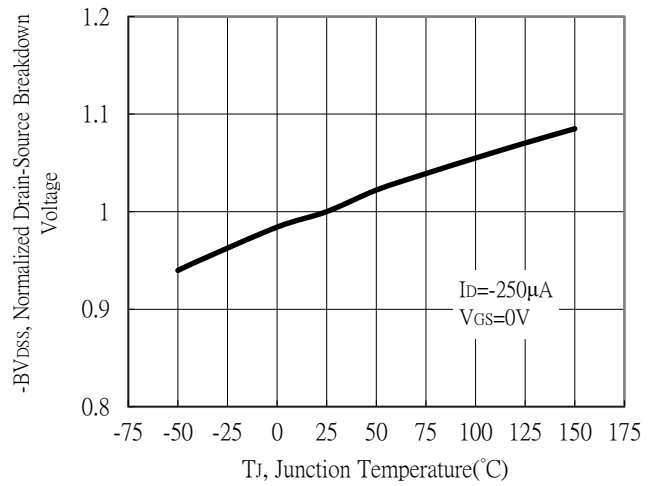


Typical Characteristics

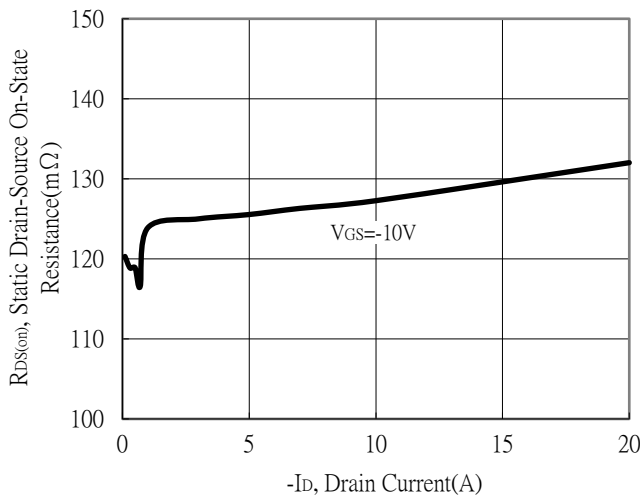
Typical Output Characteristics



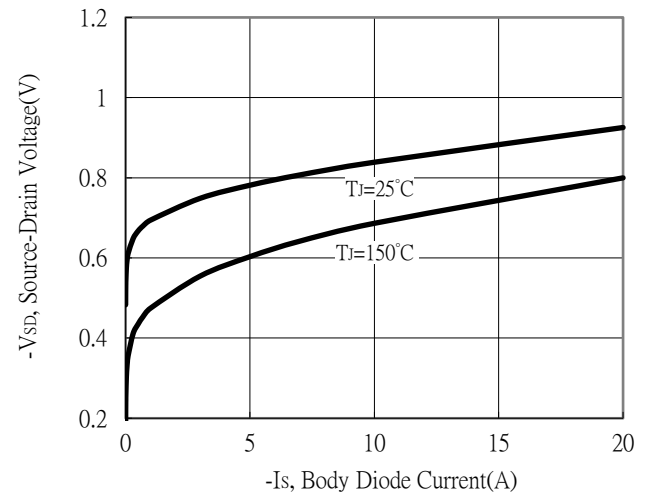
Breakdown Voltage vs Ambient Temperature



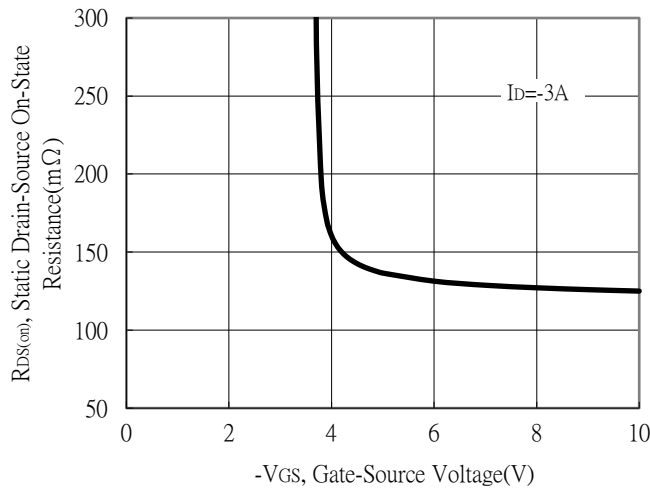
Static Drain-Source On-State resistance vs Drain Current



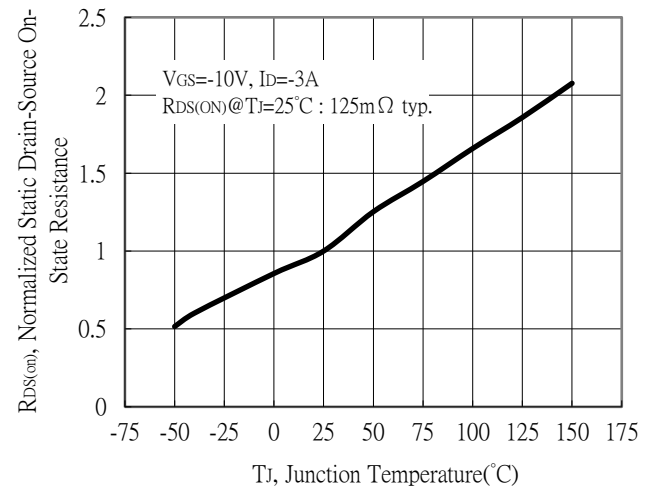
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage



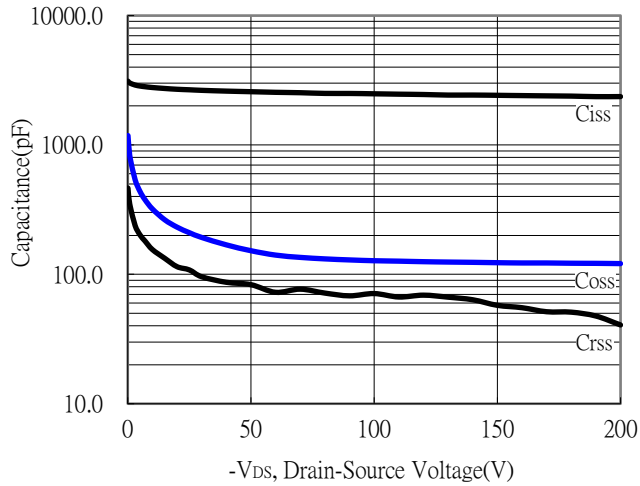
Drain-Source On-State Resistance vs Junction Temperature



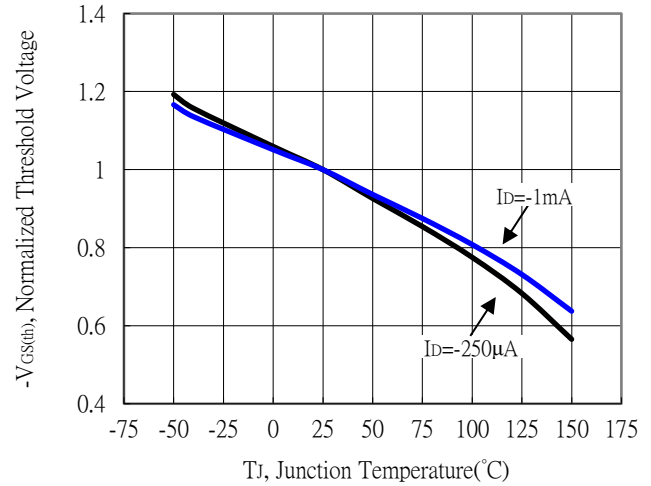


Typical Characteristics (Cont.)

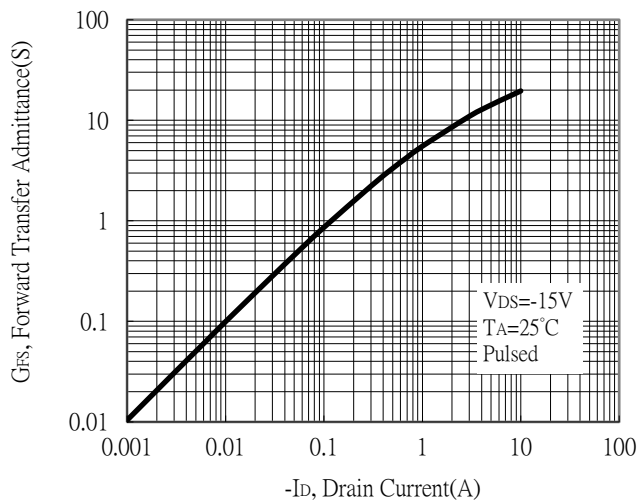
Capacitance vs Drain-to-Source Voltage



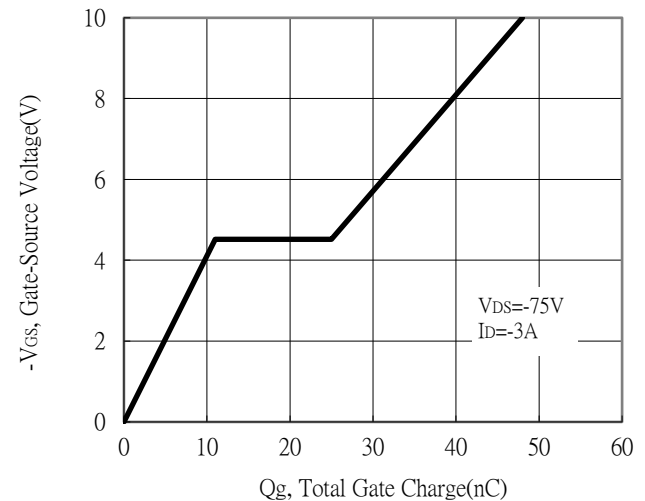
Threshold Voltage vs Junction Temperature



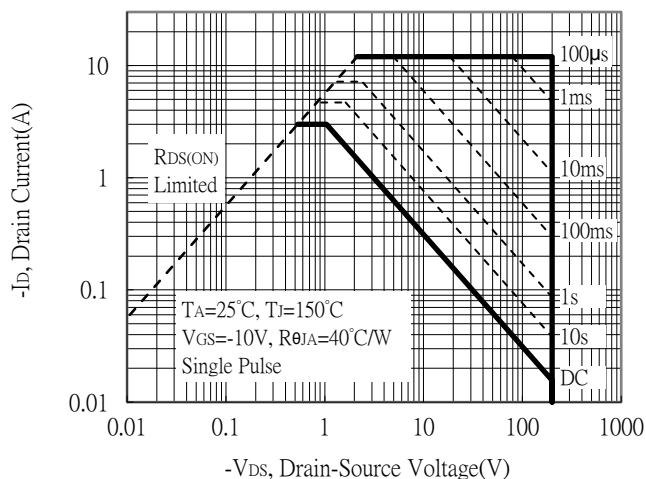
Forward Transfer Admittance vs Drain Current



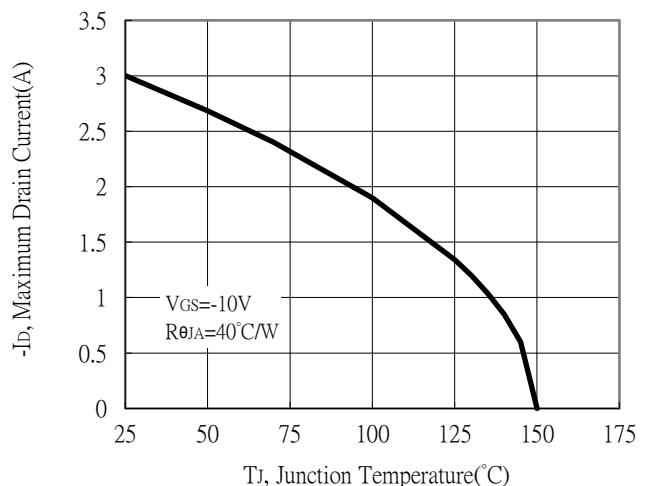
Gate Charge Characteristics



Maximum Safe Operating Area



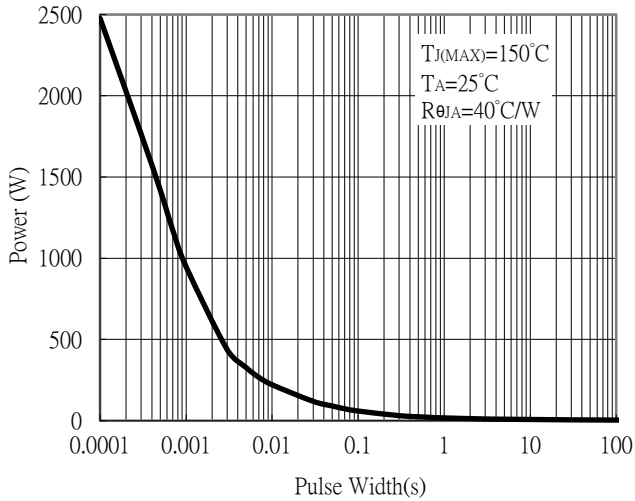
Maximum Drain Current vs Junction Temperature



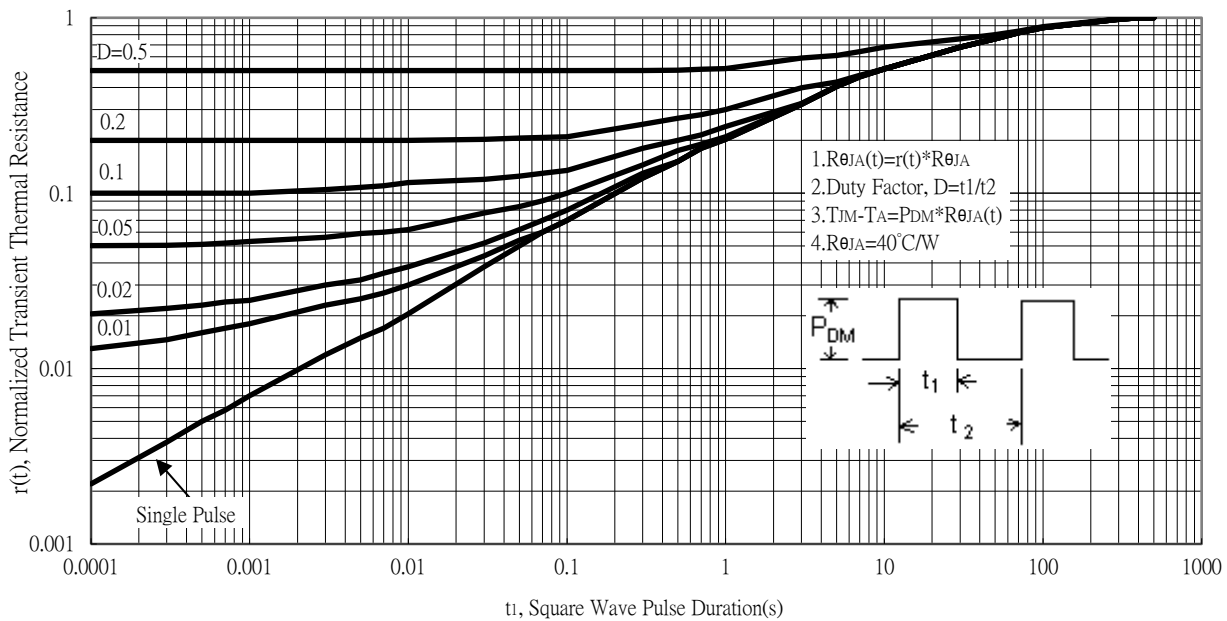


Typical Characteristics (Cont.)

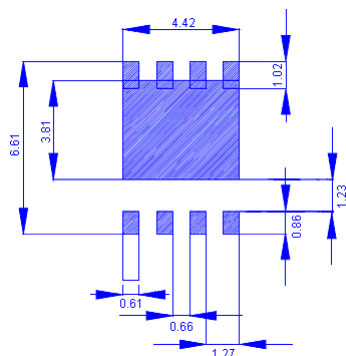
Single Pulse Power Rating, Junction to Ambient



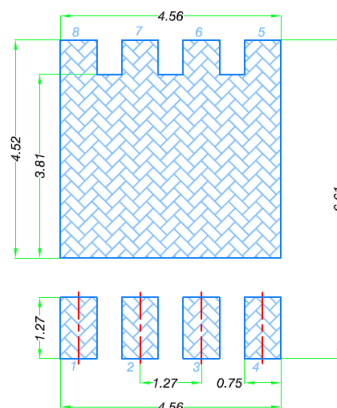
Transient Thermal Response Curves



Recommended Soldering Footprint



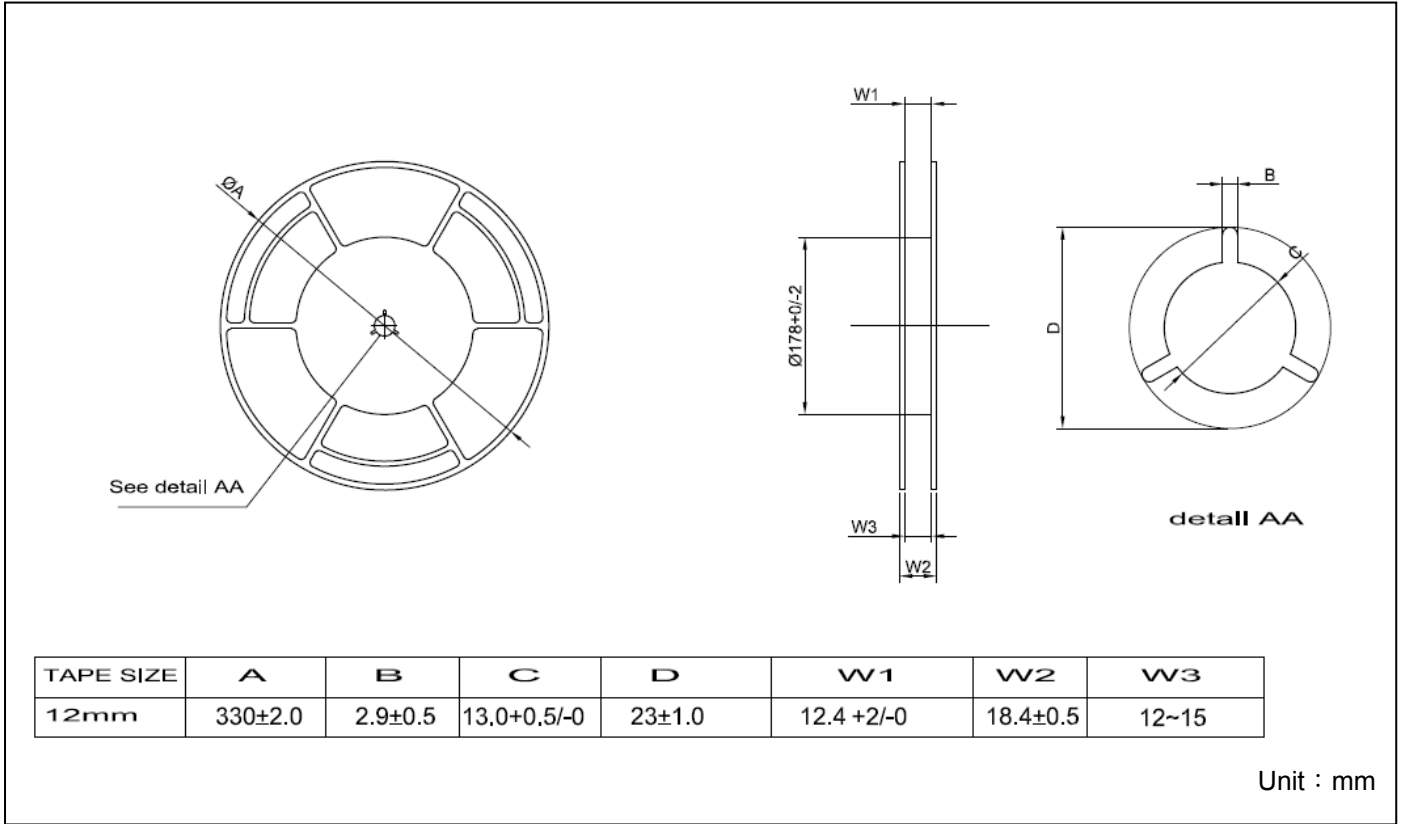
unit : mm(H forming)



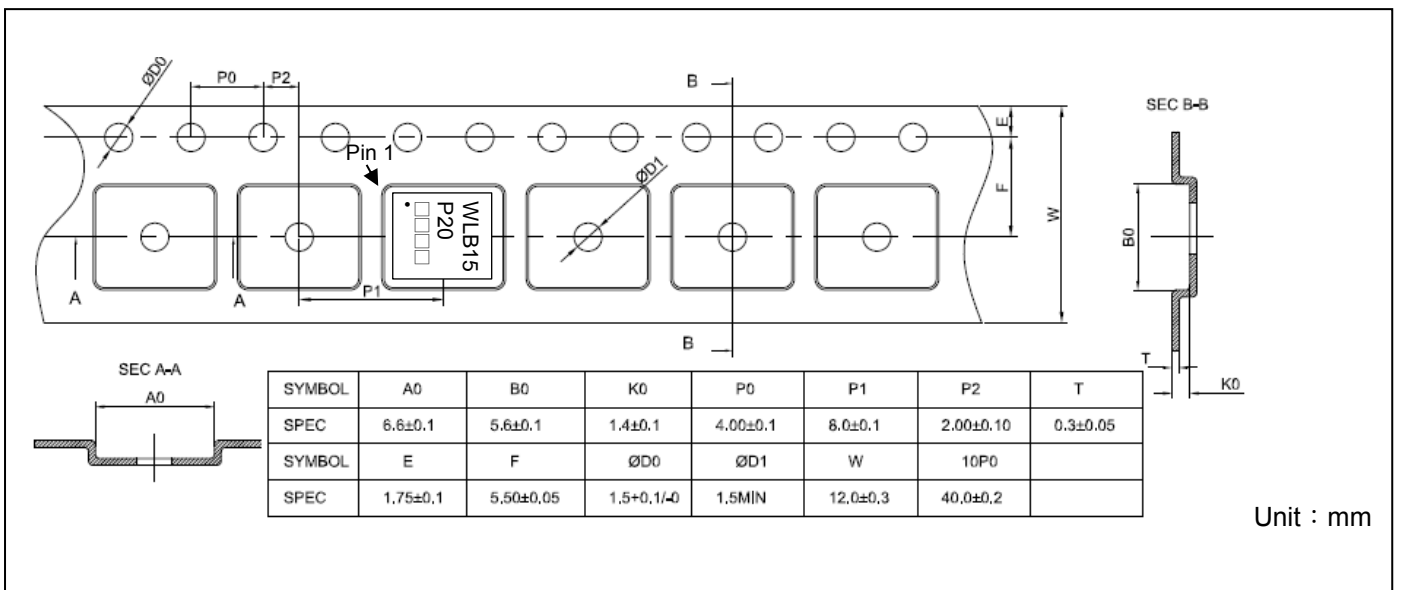
unit : mm(G forming)



Reel Dimension



Carrier Tape Dimension

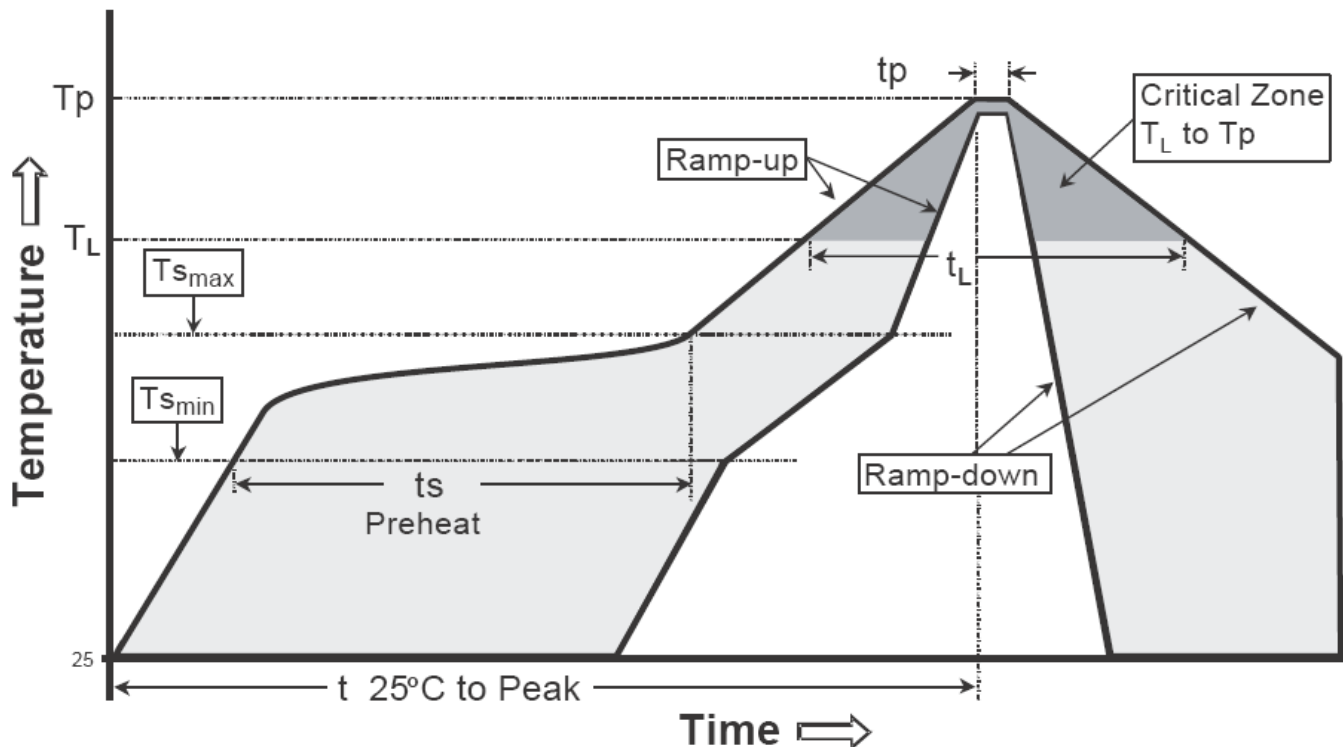




Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tl)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.



DFN5x6 Dimension (H forming)

Marking :

Device Name → **WLB15 P20**

Date Code → □ □ □ □ H

Assembly site code :
H : site 1
G : site 2

8-Lead DFN5×6 Plastic Package
CYS Package Code : H8

Date Code(counting from left to right) :
1st code: year code, the last digit of Christian year
2nd code : month code, Jan→A, Feb→B, Mar→C,
Apr→D, May→E, Jun→F, Jul→G, Aug→H,
Sep→J, Oct→K, Nov→L, Dec→M
3rd and 4th codes : production serial number, 01~99

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.000	1.200	0.0394	0.0472	E2	5.660	6.060	0.2228	0.2386
b	0.300	0.500	0.0118	0.0197	E4	3.520	3.920	0.1386	0.1543
C	0.154	0.354	0.0061	0.0139	H	0.400	0.600	0.0157	0.0236
D1	5.000	5.400	0.1969	0.2126	L	0.300	0.700	0.0118	0.0276
D2	3.800	4.250	0.1496	0.1673	L1	0.000	0.120	0.0000	0.0047
e	1.170	1.370	0.0461	0.0539	K	1.34 REF		0.0527 REF	
E1	5.950	6.350	0.2343	0.2500					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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DFN5x6 Dimension (G forming)

Marking:

Device Code → WLB15
P20

Date Code → □□□□ G

Assembly site code:
H : site 1
G : site 2

Date Code (counting from left to right):
1st code: year code, the last digit of Christian year
2nd code: month code, Jan→A, Feb→B, Mar→C, Apr→D, May→E, Jun→F, Jul→G, Aug→H, Sep→J, Oct→K, Nov→L, Dec→M
3rd and 4th codes: production serial number, 01~99

8-Lead DFN5x6 Plastic Package
CYS Package Code : H8

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	1.00	1.20	0.039	0.047	E2	3.52	3.92	0.138	0.154
A1	0.00	0.05	0.000	0.001	e	1.27	BSC	0.050	BSC
b	0.33	0.50	0.012	0.019	H	0.40	0.60	0.015	0.023
c	0.20	0.30	0.007	0.011	K	1.10	-	0.043	-
D1	5.00	5.40	0.196	0.212	L	0.50	0.70	0.019	0.027
D2	3.80	4.25	0.149	0.167	L1	0.08	0.22	0.003	0.008
E	6.00	6.30	0.236	0.248	α	0°	12°	0°	12°
E1	5.76	5.96	0.226	0.234					

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